

ON Semiconductor

Is Now

The logo for onsemi, featuring the word "onsemi" in a dark teal, lowercase, sans-serif font. The letter "i" is stylized with a white dot and a teal vertical bar. A small orange triangle is positioned above the top right of the "i". A trademark symbol (TM) is located to the right of the logo.

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MC14020B

14-Bit Binary Counter

The MC14020B 14-stage binary counter is constructed with MOS P-Channel and N-Channel enhancement mode devices in a single monolithic structure. This part is designed with an input wave shaping circuit and 14 stages of ripple-carry binary counter. The device advances the count on the negative-going edge of the clock pulse. Applications include time delay circuits, counter controls, and frequency-dividing circuits.

Features

- Fully Static Operation
- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- Buffered Outputs Available from stages 1 and 4 thru 14
- Common Reset Line
- Pin-for-Pin Replacement for CD4020B
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V_{in}, V_{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to $V_{DD} + 0.5$	V
I_{in}, I_{out}	Input or Output Current (DC or Transient) per Pin	± 10	mA
P_D	Power Dissipation, per Package (Note 1)	500	mW
T_A	Ambient Temperature Range	-55 to +125	$^{\circ}C$
T_{stg}	Storage Temperature Range	-65 to +150	$^{\circ}C$
T_L	Lead Temperature (8-Second Soldering)	260	$^{\circ}C$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: "D/DW" Packages: -7.0 mW/ $^{\circ}C$ From 65 $^{\circ}C$ To 125 $^{\circ}C$

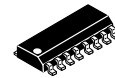
This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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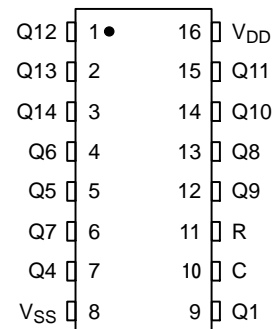


SOIC-16
D SUFFIX
CASE 751B

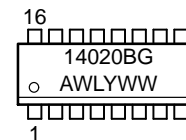


TSSOP-16
DT SUFFIX
CASE 948F

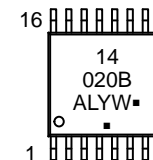
PIN ASSIGNMENT



MARKING DIAGRAMS



SOIC-16



TSSOP-16

- A = Assembly Location
- WL, L = Wafer Lot
- YY, Y = Year
- WW, W = Work Week
- G or ■ = Pb-Free Indicator



(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

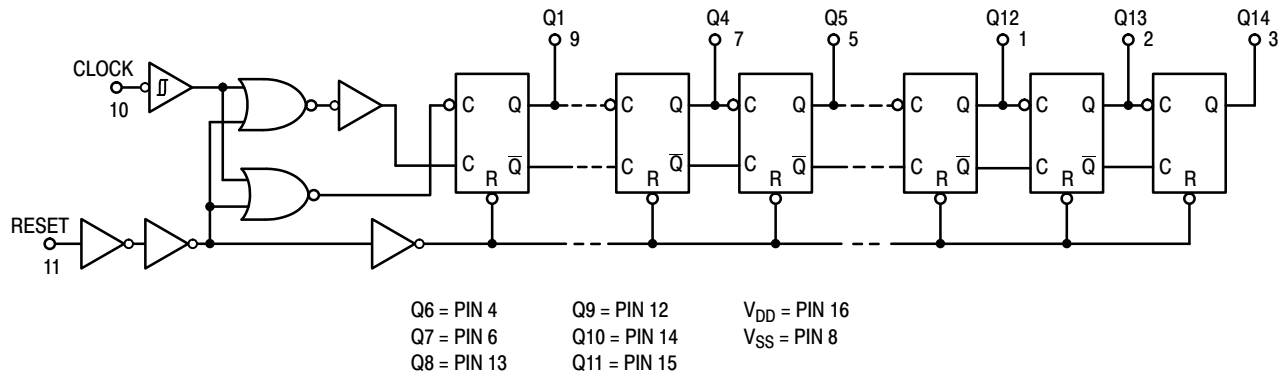
MC14020B

TRUTH TABLE

Clock	Reset	Output State
	0	No Change
	0	Advance to Next State
X	1	All Outputs are Low

X = Don't Care

LOGIC DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping [†]
MC14020BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14020BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
NLV14020BDR2G*	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC14020BDTG	TSSOP-16 (Pb-Free)	96 Units / Rail

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

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ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V _{DD} Vdc	-55°C		25°C			125°C		Unit	
			Min	Max	Min	Typ (Note 2)	Max	Min	Max		
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0	-	0.05	-	0	0.05	-	0.05	Vdc
			10	-	0.05	-	0	0.05	-	0.05	
			15	-	0.05	-	0	0.05	-	0.05	
	"1" Level	V _{OH}	5.0	4.95	-	4.95	5.0	-	4.95	-	Vdc
			10	9.95	-	9.95	10	-	9.95	-	
			15	14.95	-	14.95	15	-	14.95	-	
Input Voltage (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	"0" Level	V _{IL}	5.0	-	1.5	-	2.25	1.5	-	1.5	Vdc
			10	-	3.0	-	4.50	3.0	-	3.0	
			15	-	4.0	-	6.75	4.0	-	4.0	
	"1" Level	V _{IH}	5.0	3.5	-	3.5	2.75	-	3.5	-	Vdc
			10	7.0	-	7.0	5.50	-	7.0	-	
			15	11	-	11	8.25	-	11	-	
Output Drive Current (V _{OH} = 2.5 Vdc) (V _{OH} = 4.6 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc)	Source	I _{OH}	5.0	-3.0	-	-2.4	-4.2	-	-1.7	-	mAdc
			5.0	-0.64	-	-0.51	-0.88	-	-0.36	-	
			10	-1.6	-	-1.3	-2.25	-	-0.9	-	
			15	-4.2	-	-3.4	-8.8	-	-2.4	-	
	Sink	I _{OL}	5.0	0.64	-	0.51	0.88	-	0.36	-	mAdc
			10	1.6	-	1.3	2.25	-	0.9	-	
15			4.2	-	3.4	8.8	-	2.4	-		
Input Current	I _{in}	15	-	±0.1	-	±0.00001	±0.1	-	±1.0	μAdc	
Input Capacitance (V _{in} = 0)	C _{in}	-	-	-	-	5.0	7.5	-	-	pF	
Quiescent Current (Per Package)	I _{DD}	5.0	-	5.0	-	0.005	5.0	-	150	μAdc	
		10	-	10	-	0.010	10	-	300		
		15	-	20	-	0.015	20	-	600		
Total Supply Current (Notes 3 & 4) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	I _T	5.0	I _T = (0.42 μA/kHz)f + I _{DD}							μAdc	
		10	I _T = (0.85 μA/kHz)f + I _{DD}								
		15	I _T = (1.43 μA/kHz)f + I _{DD}								

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
- The formulas given are for the typical characteristics only at 25°C.
- To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where: I_T is in μA (per package), C_L in pF, V = (V_{DD} - V_{SS}) in volts, f in kHz is input frequency, and k = 0.001.

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SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

Characteristic	Symbol	V_{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time t_{TLH} , $t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ t_{TLH} , $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ t_{TLH} , $t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	t_{TLH} , t_{THL}	5.0 10 15	– – –	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q1 t_{PHL} , $t_{PLH} = (1.7 \text{ ns/pF}) C_L + 175 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.66 \text{ ns/pF}) C_L + 82 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.5 \text{ ns/pF}) C_L + 55 \text{ ns}$	t_{PLH} , t_{PHL}	5.0 10 15	– – –	260 115 80	520 230 160	ns
Clock to Q14 t_{PHL} , $t_{PLH} = (1.7 \text{ ns/pF}) C_L + 1735 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.66 \text{ ns/pF}) C_L + 772 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.5 \text{ ns/pF}) C_L + 535 \text{ ns}$		5.0 10 15	– – –	1820 805 560	3900 1725 1200	ns
Propagation Delay Time Reset to Q_n $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 285 \text{ ns}$ $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 122 \text{ ns}$ $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 90 \text{ ns}$	t_{PHL}	5.0 10 15	– – –	370 155 115	740 310 230	ns
Clock Pulse Width	t_{WH}	5.0 10 15	500 165 125	140 55 38	– – –	ns
Clock Pulse Frequency	f_{max}	5.0 10 15	1.0 3.0 4.0	2.0 6.0 8.0	– – –	MHz
Clock Rise and Fall Time	t_{TLH} , t_{THL}	5.0 10 15	No Limit			–
Reset Pulse Width	t_{WL}	5.0 10 15	3000 550 420	320 120 80	– – –	ns
Reset Recovery Time	t_{rec}	5.0 10 15	– – –	65 25 15	130 50 30	ns

5. The formulas given are for the typical characteristics only at 25°C .

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

MC14020B

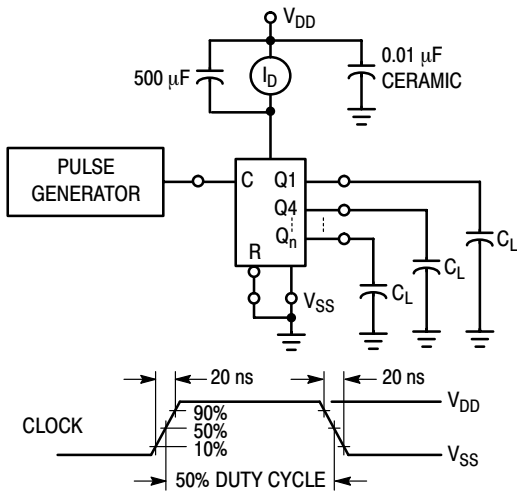


Figure 1. Power Dissipation Test Circuit and Waveform

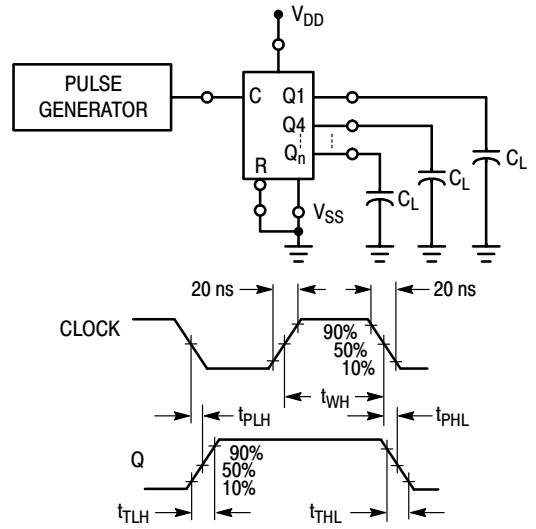


Figure 2. Switching Time Test Circuit and Waveforms

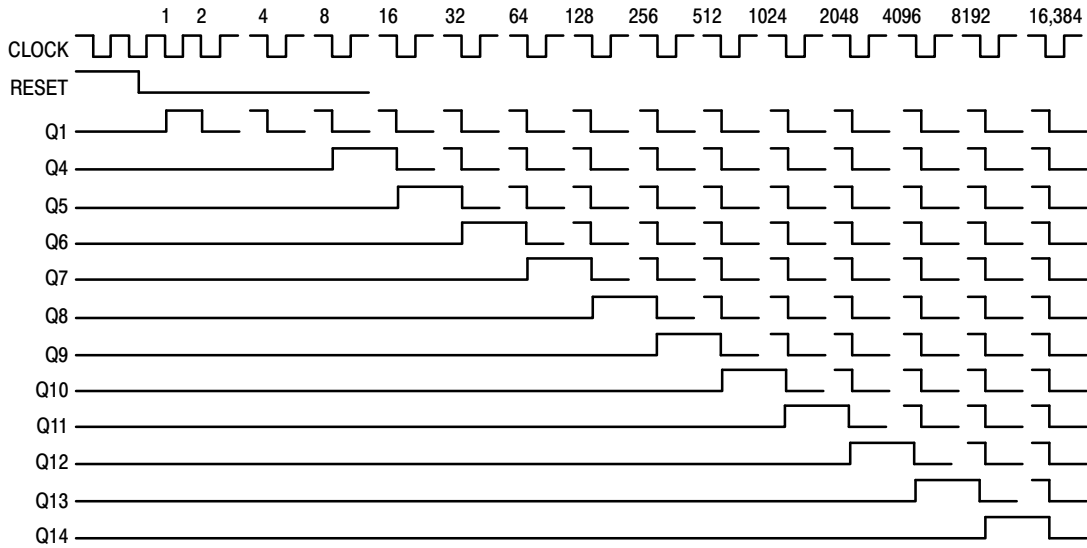
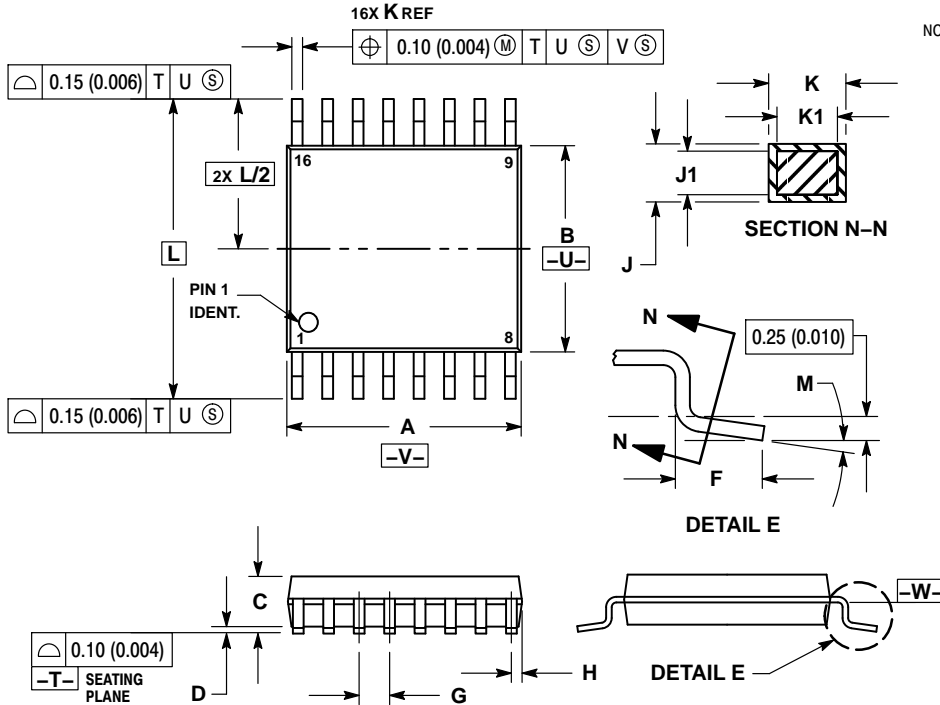


Figure 3. Timing Diagram

MC14020B

PACKAGE DIMENSIONS

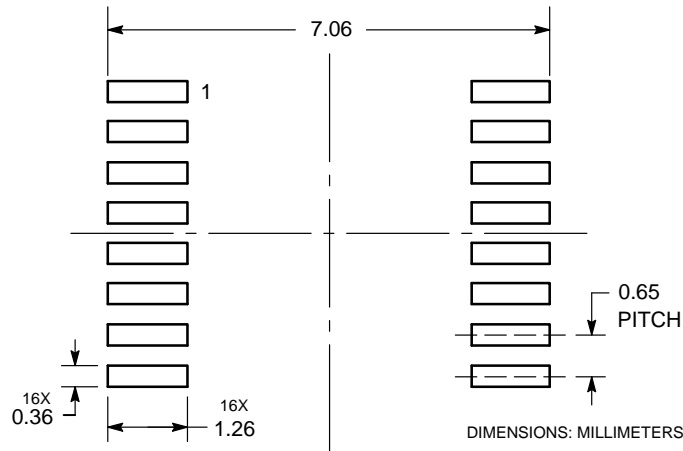
TSSOP-16
DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948F
ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.